

App. Serial No. 10/510,588  
Docket No.: NL021100US

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**In the Claims:**

Please amend claim 4 as indicated below. This listing of claims replaces all prior versions.

Claims 1-3 (*Cancelled*).

4. (Currently Amended) An electronic device comprising a carrier having, between a first side and an opposite second side,

a first etch mask,

a first patterned metal layer,

a patterned intermediate layer,

a second patterned metal layer and

a second etch mask for use of etching of the second metal layer,

wherein the first and second etch mask each have an adhesive layer for solder,

wherein the first patterned metal layer is electroconductively connected to ~~[[an]]~~ a first electric element and to the second metal layer, and the first patterned metal layer further includes parts projecting with respect to the intermediate layer, the projecting parts of the first metal layer are anchored in an the envelope in which the first electric element is present on the first side of the carrier,

wherein contacts of the electric element are electroconductively connected to the first metal layer, and

wherein the ~~electronic device includes a~~ the first electric element and a second electric element, ~~the electric elements~~ are interconnected by an interconnect track that is defined in the first metal layer, while a corresponding interconnect track is absent in the second metal layer.

5. (*Cancelled*).

6. (Previously Presented) The electronic device as recited in claim 4, wherein the first and the second etch mask comprise an adhesive layer for solder.

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7. (Previously Presented) -The electronic device as recited in claim 6, wherein the adhesive layer for solder comprises a material selected from the group composed of Ag, NiPd, NiPdAu.

8. (Previously Presented) The electronic device as recited in claim 4, wherein the intermediate layer comprises an electroconductive material that can suitably be used as a solder stop.

9. (Previously Presented) The electronic device as recited in claim 8, wherein the intermediate layer comprises a material selected from the group composed of Al, an alloy of Al, FeNi, FeCrNi and stainless steel, and that the first patterned metal layer and the second patterned metal layer contain copper.

Claims 10-12 (*Cancelled*).

13. (Previously Presented) The electronic device as recited in claim 4, wherein the intermediate layer is made from a material that can be selectively etched with respect to the first patterned metal layer.

14. (Previously Presented) The electronic device as recited in claim 13, wherein the intermediate layer is a metal.

15. (Previously Presented) The electronic device as recited in claim 14, wherein the intermediate layer comprises a material selected from the group composed of Al, an alloy of Al, FeNi, FeCrNi and stainless steel, and that the first patterned metal layer and the second patterned metal layer contain copper.

16. (Previously Presented) The electronic device as recited in claim 4, wherein the first electric element is a semiconductor element which is placed on the first side of the carrier with a flip-chip technique.

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17. (Previously Presented) The electronic device as recited in claim 16, wherein connection conductors are defined in the second patterned metal layer and the corresponding etch mask, said connection conductors are laterally displaced with respect to contacts in the semiconductor element.